

# Microelectronics Packaging Handbook



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This thoroughly revised and updated three volume set continues to be the standard reference in the field, providing the latest in microelectronics design methods, modeling tools, simulation techniques, and manufacturing procedures. Unlike reference books that focus only on a few aspects of microelectronics packaging, these outstanding volumes discuss state-of-the-art packages that meet the power, cooling, protection, and interconnection requirements of increasingly dense and fast microcircuitry. Providing an excellent balance of theory and practical applications, this dynamic compilation features step-by-step examples and vital technical data, simplifying each phase of package design and production. In addition, the volumes contain over 2000 references, 900 figures, and 250 tables. Part I: Technology Drivers covers the driving force of microelectronics packaging - electrical, thermal, and reliability. It introduces the technology developer to aspects of manufacturing that must be considered during product development. Part II: Semiconductor Packaging discusses the interconnection of the IC chip to the first level of packaging and all first level packages. Electrical test, sealing, and encapsulation technologies are also covered in detail. Part III: Subsystem Packaging explores board level packaging as well as connectors, cables, and optical packaging.

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